



DMMT5401

MATCHED PNP SMALL SIGNAL SURFACE MOUNT TRANSISTOR

Features

Epitaxial Planar Die Construction Complementary NPN Type Available (DMMT5551) Ideal for Low Power Amplification and Switching Intrinsically Matched PNP Pair (Note 1) 2% Matched Tolerance, h_{FE}, V_{CE(SAT)}, V_{BE(SAT)} Lead Free/RoHS Compliant (Note 4) "Green" Device, Note 5 and 6



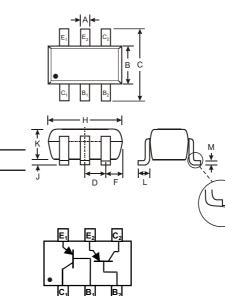
Case: SOT-26 Case Material: Mo

Case Material: Molded Plastic, "Green" Molding Compound, Note 7. UL Flammability Classification Rating 94V-0 Moisture Sensitivity: Level 1 per J-STD-020C

Terminal Connections: See Diagram

Terminals: Solderable per MIL-STD-202, Method 208 Lead Free Plating (Matte Tin Finish annealed over Copper leadframe). Marking (See Page 2): K4S

Order & Date Code Information: See Page 2 Weight: 0.006 grams (approximate)



	SOT-26									
Dim	Min	Max	Тур							
Α	0.35	0.50	0.38							
В	1.50	1.70	1.60							
С	2.70	3.00	2.80							
D			0.95							
F			0.55							
н	2.90	3.10	3.00							
J	0.013	0.10	0.05							
к	1.00	1.30	1.10							
L	0.35	0.55	0.40							
М	0.10	0.20	0.15							
	0	8								
All C	All Dimensions in mm									

Maximum Ratings @ T_A = 25 C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-160	V
Collector-Emitter Voltage	V _{CEO}	-150	V
Emitter-Base Voltage	V _{EBO}	-5.0	V
Collector Current - Continuous (Note 2)	lc	-200	mA
Power Dissipation (Note 2, 3)	Pd	300	mW
Thermal Resistance, Junction to Ambient (Note 2)	R JA	417	°C/W
Operating and Storage and Temperature Range	T _j , T _{STG}	-55 to +150	С

Notes: 1. Built with adjacent die from a single wafer.

2. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.

Maximum combined dissipation.

4. No purposefully added lead.

5. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.

6. Product manufactured with Date Code 0627 (week 27, 2006) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 0627 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.



Electrical Characteristics @ T_A = 25 C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
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OFF CHARACTERISTICS (Note 7)	ii		1		
Collector-Base Breakdown Voltage	V _{(BR)CBO}	-160		V	$I_{C} = -100 A, I_{E} = 0$
Collector-Emitter Breakdown Voltage	V _{(BR)CEO}	-150		V	$I_{C} = -1.0 \text{mA}, I_{B} = 0$
Emitter-Base Breakdown Voltage	V _{(BR)EBO}	-5.0		V	$I_E = -10$ A, $I_C = 0$
Collector Cutoff Current	I _{СВО}		-50	nA A	$ \begin{array}{l} V_{CB} = -120V, \ I_E = 0 \\ V_{CB} = -120V, \ I_E = 0, \ T_A = 100 \ C \end{array} $
Emitter Cutoff Current	I _{EBO}		-50	nA	$V_{EB} = -3.0V, I_C = 0$
ON CHARACTERISTICS (Note 7)					
DC Current Gain (Note 8)	h _{FE}	50 60 50	240		$ \begin{array}{ll} I_C = & -1.0mA, \ V_{CE} = & -5.0V \\ I_C = & -10mA, \ V_{CE} = & -5.0V \\ I_C = & -50mA, \ V_{CE} = & -5.0V \end{array} $
Collector-Emitter Saturation Voltage	V _{CE(SAT)}		-0.2 -0.5	V	$I_{C} = -10mA, I_{B} = -1.0mA$ $I_{C} = -50mA, I_{B} = -5.0mA$
Base-Emitter Saturation Voltage	V _{BE(SAT)}		-1.0	V	$I_{C} = -10mA, I_{B} = -1.0mA$ $I_{C} = -50mA, I_{B} = -5.0mA$
SMALL SIGNAL CHARACTERISTICS					
Output Capacitance	C _{obo}		6.0	pF	$V_{CB} = -10V, f = 1.0MHz, I_E = 0$
Small Signal Current Gain	h _{fe}	40	200		$V_{CE} = -10V, I_C = -1.0mA, f = 1.0kHz$
Current Gain-Bandwidth Product	fT	100	300	MHz	$V_{CE} = -10V, I_C = -10mA, f = 100MHz$
Noise Figure	NF		8.0	dB	$ \begin{array}{l} V_{CE} = -5.0V, \ I_{C} = -200 \ \ A, \\ R_{S} = 10 \ \ f = 1.0 \text{kHz} \end{array} $

Ordering Information (Note 6 & 9)

Device	Packaging	Shipping		
DMMT5401-7-F	SOT-26	3000/Tape & Reel		

Notes: 6. Product manufactured with Date Code 0627 (week 27, 2006) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 0627 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

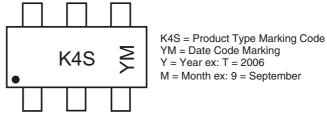
7. Short duration pulse test used to minimize self-heating effect.

8. The DC Current Gain, hFE, (matched at I_C = -10mA and V_{CE} = -5V) Collector Emitter Saturation Voltage, V_{CE(SAT)}, and Base

Emitter Saturation Voltage, VBE(SAT) are matched with typical matched tolerances of 1% and maximum of 2%.

9. For Packaging Details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



YM = Date Code Marking Y = Year ex: T = 2006

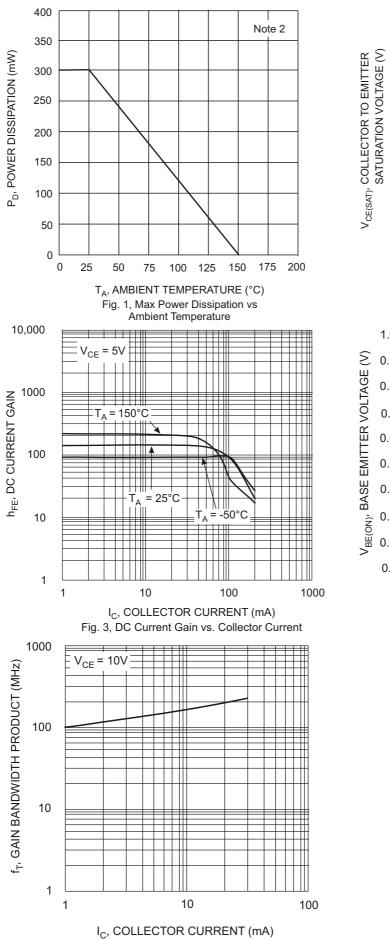
M = Month ex: 9 = September

Date Code Key

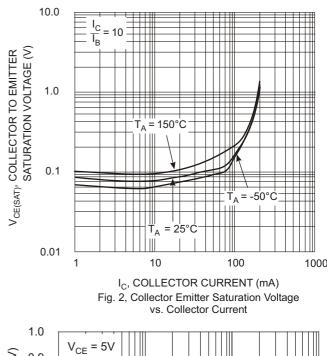
Year	2004	2005	2006	2007	2008	2009	2010	2011	2012
Code	R	S	Т	U	V	W	Х	Y	Z

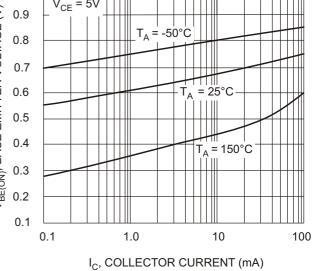
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	Ν	D

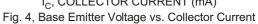














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